

LINEAR TECHNOLOGY MATERIALS DECLARATION

ltc2757bclx#pbf

(Engineering Calculation)

LQFP 7mm X 7mm

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TOTAL MASS (g) : 0.197956

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.006180	1000000	31219.0136719		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.042592	693000	215158.609375		
		Iron (Fe)	7439-89-6	0.000651	10599.9990234	3288.60473633		
		Phosphorus (P)	7723-14-0	0.000000	0	0		
		Zinc (Zn)	7440-66-6	0.000602	9800	3041.07519531		
		Nickel (Ni)	7440-02-0	0.013288	216200.015625	67125.921875		
		Silicon (Si)	7440-21-3	0.000369	25400	7885.57910156		
		Magnesium (Mg)	7439-95-4	0.001561	25400	7885.57910156		
		Tin (Sn)	7440-31-5	0.002397	39000	12108.7333984		
Lead Frame Total:				0.061460	1000000	310472.5625		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.002712	1000000	13701.4863281		
		External Plating Total:				0.002712	1149333	13701.4863281
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.001274	1000000	6435.76416016		
		Internal Plating Total:				0.001274	1000000	6435.76416016
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000641	750000	3238.08837891		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000214	250000	1081.04675293		
Die Attach Total:				0.000855	1000000	4319.13525391		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.015015	123000	75850.078125		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.106689	874000	538952.3125		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000366	3000	1848.89294434		
		Encapsulation Total:				0.122070	1000000	616651.3125
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.001008	1000000	5092.03320312		
					TOTAL MASS (g) :	0.197956		